

Technical Data Sheet

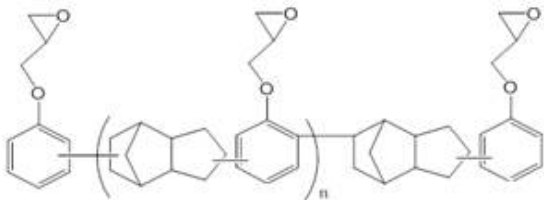
KES-7660

DCPD-Phenol Epoxy

General Description

DCPD-苯酚環氧樹脂KES-7660是衍生自雙環戊二烯和苯酚的固體型環氧樹脂。因為它具有優異的電氣性能, KES-7660設計用於半導體EMC以及CCL應用。特別是該產品具有低Dk (介電常數) 和Df (低介電損耗) 特性, 因此可用於高速PCB。

Chemical Structure



Resin Properties

Property	Typical values
EEW (g/eq)	240~280
S.P. (°C)*	57~68
Hy-Cl (ppm)	500 Max
Total-Cl (ppm)	1500 Max
ICI (cps)	10~200

* Mettler 2°C/min

Usage

1. CCL laminate for high speed PCB
2. Carbon fiber prepreg laminate
3. Electronic encapsulation and transfer molding
4. Electrical heat resistance molding compound
5. Lead free type CCL laminate varnish additives
6. High temperature adhesives and structural composites
7. Tooling, casting & molding compounds

Storage

Keep in cool, dry, ventilate condition and in closed containers.

Keep away from heat sources and direct sunlight. Recommended safe handing procedures are discussed in the information on the MSDS should reviewed and understood before working.

Packaging

Paper Bag of 20 kg net weight